MicroAssembly Technologies, Ltd.

MODEL 6495/6/7 DIE ATTACH SYSTEM

MCM, Hybrid, Silver Glass, Flip Chip, Eutectic die attach system.

Versatile tabletop machine. Friendly menu driven operator interface.

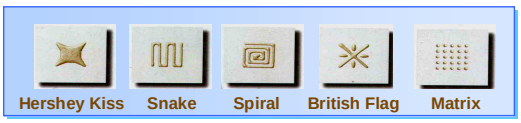
Fully programmed control of all process functions such as Velocities and Times, Dispensing, Bond and Pickup Forces, Bond Line Thickness, Scrubbing, etc.

Flexible, set up new process in minutes. High yield and accuracy, ideal solution for process labs and low to medium volume production.

Dispensing of adhesive and flux in single/multi dot and shape patterns.

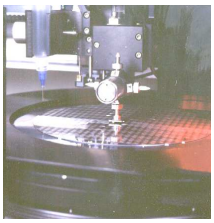
Stamping (Pin Transfer) 100 um and under adhesive dots.

Library of pre-taught dispense shapes.



Programmable **Bond Line Thickness** control.

Wafer Mapping capability or **Ink Dot** recognition.



Pick from Wafer up to 8" (automatic or manual).

Pick from 2" or 4" Waffle or Gel-Pak.

Specializing in unusual die sizes and aspect ratios. Unique sensors (CCD and other) attachment capability.

Advanced Vision and **Pattern Recognition System** for die and substrates.

Motorized Pickup and Magazine Handler Options upgrade the machine to **Fully Automatic**.

Performs cold and heated processes on Silicon, Glass, BGA, Lead Frame, PCB and other substrates.

Ultra-Sonic bonding head available for Eutectic and Flip Chip applications.

Specification Highlights

Large 12" x 12" Work Area.
Die size range: 0.010" to over 1".
Die Material: GaAs, Si, Glass, Metal, etc.
Pickup/Bond Force: 20 – 3000 grams.
Placement Accuracy: 25µm @ 3σ.
Throughput: up to 600 CPH.
Up to 211 components/package.

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